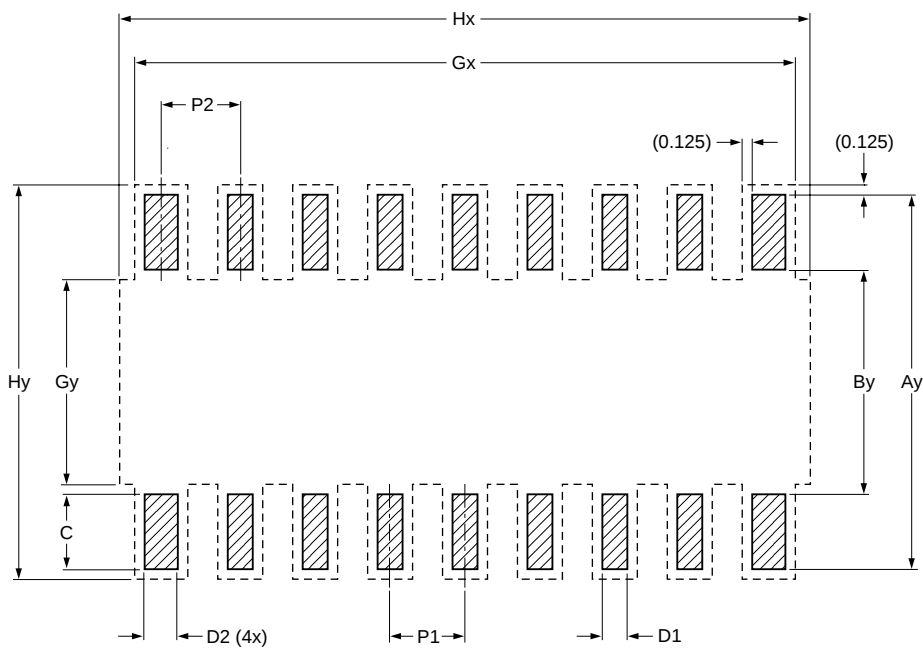


Footprint information for reflow soldering of VSO56 package

SOT190-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.750	0.825	16.200	11.900	2.150	0.450	0.600	21.250	11.600	22.100	16.450